

Excellent Integrated System Limited

Stocking Distributor

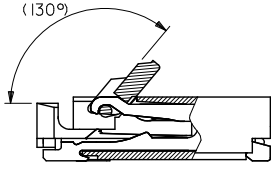
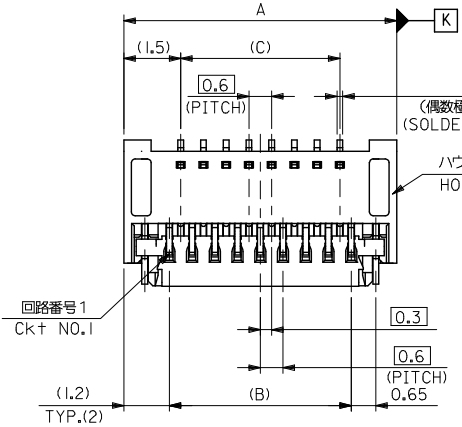
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[500797-3194](#)

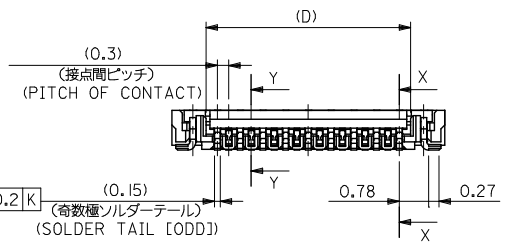
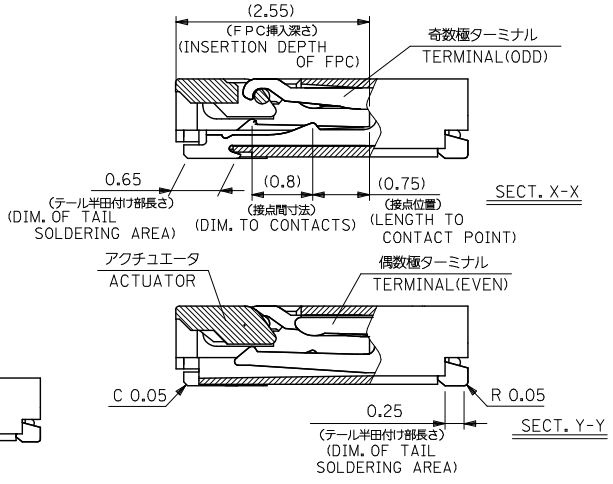
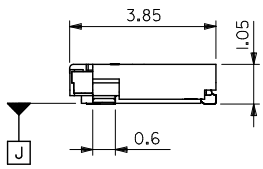
For any questions, you can email us directly:

sales@integrated-circuit.com

10 9 8 7 6 5 4 3 2 1



アクチュエータを開口した状態
WHEN ACTUATOR IS OPENED

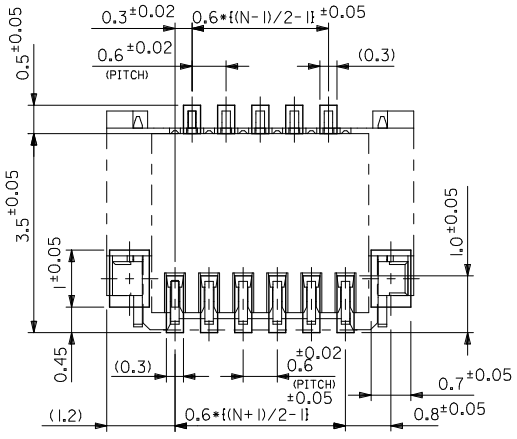


10.2	9.0	9.6	12.0	500797-3394	500797-3350	33
9.6	8.4	9.0	11.4	500797-3194	500797-3150	31
8.4	7.2	7.8	10.2	500797-2794	500797-2750	27
7.2	6.0	6.6	9.0	500797-2394	500797-2350	23
3.6	2.4	3.0	5.4	500797-1194	500797-1150	11
D	C	B	A	EMBOSSED TAPE		MATERIAL NO. CKT.
				ORDER No. オダー番号		

REVISED EC NO. J2016-1099 DRAWN: TAKAHASHI 04/2016/04/19 CHK: OKATAKASHI 2016/04/26 APPR: IKUSUHARA01 2016/04/28 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL No.
	0.25 UNDER	UNDER	±0.03	MM ONLY	---	METRIC	500797-***50
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	THIRD ANGLE PROJECTION	
	0.5 OVER	1.0 UNDER	±0.1	YMAEDA	2006/03/07	TITLE	
	1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE	0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM)	
10 OVER	30 UNDER	±0.25	MTANAKA	2006/03/07	GOLD PLATING -LEAD FREE-		
30 OVER		±0.3	APPROVED BY	DATE	molex		
ANGULAR	±3 °		NUKITA	2006/03/07	DOCUMENT NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SD-500797-005		SHEET NO. 1 OF 2

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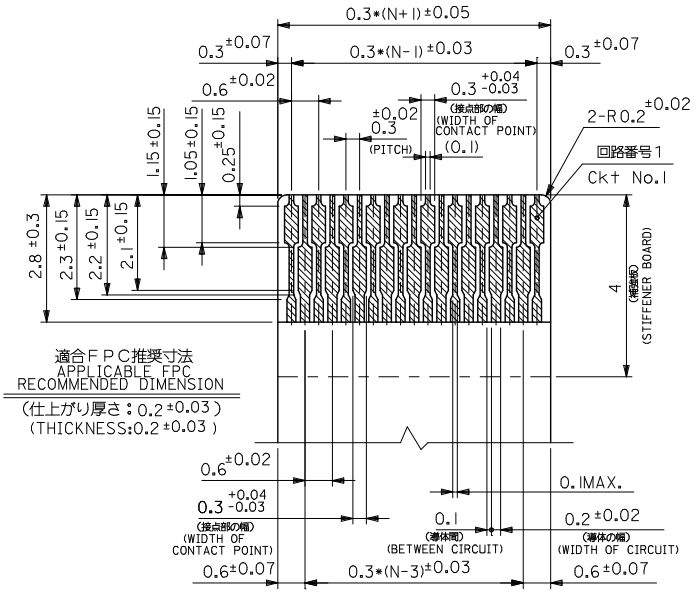
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参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

- 使用材料 MATERIAL
ハウジング : 液晶ポリマー ガラス充填 UL94V-0
HOUSING : LIQUID CRYSTAL POLYMER (GLASS FILLED) UL94V-0
アクチュエータ : 46 ナylon ガラス充填 UL94V-0
ACTUATOR : 46 NYLON (GLASS FILLED) UL94V-0
ターミナル : 銅合金 (t=0.15), ニッケル下地金メッキ
TERMINAL : COPPER ALLOY, GOLD OVER NICKEL PLATING.
金具 : リン青銅 (t=0.15), ニッケル下地スズメッキ
FITTING NAIL : PHOSPHOR-BRONZE, TIN OVER NICKEL PLATING.
- △ ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 □ に対し、上方向 0.1MAXIMUM、下方向 0.15MAXIMUM とする。
又、相互のバツキ量は 0.1MAXIMUM とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM □
UPPER DIRECTION : 0.1 MAXIMUM, LOWER DIRECTION : 0.15 MAXIMUM.
OFFSET BETWEEN SOLDER TAILS AND FITTING NAILS : 0.1 MAXIMUM.



適用FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2±0.03)
(THICKNESS: 0.2±0.03)

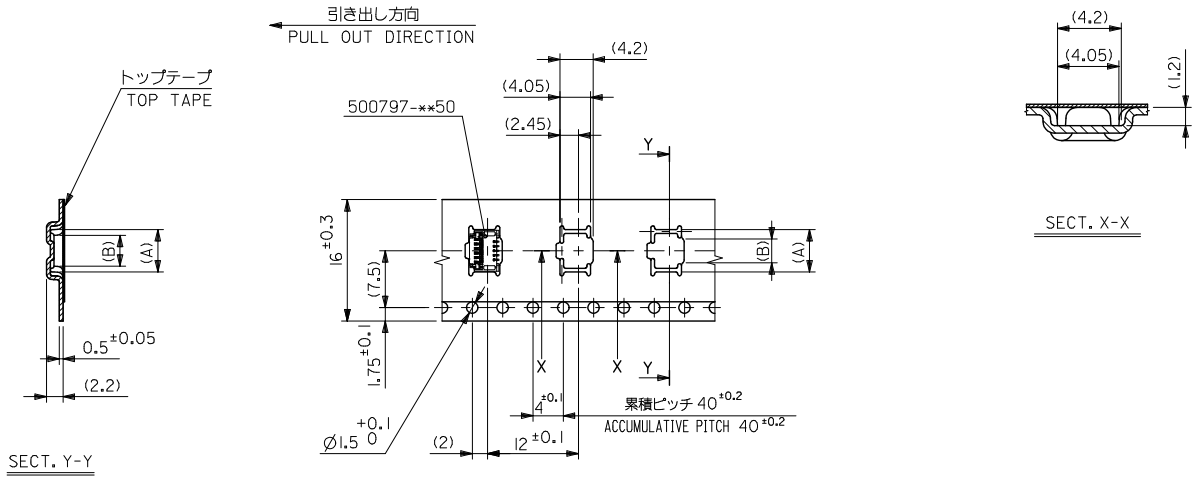
FPCについて:
打抜き方向は導体側から補強板側を推奨いたします。
導体側については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。
補強フィルム材質はポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。

ABOUT FPC
RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED CONDUCTOR SPEC :
THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER
RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO. J2016-1099 DRAWN: TAKAHASHI 04/2016/04/19 CHK: KIKUCHI 2016/04/26 APPR: IKUSABARA 2016/04/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.
	0.25 UNDER	UNDER	±0.03	MM ONLY	---	METRIC	500797-***50
	0.25 OVER	0.5 UNDER	±0.05	DRAWN BY	DATE	TITLE	THIRD ANGLE PROJECTION
	0.5 OVER	1.0 UNDER	±0.1	YMAEDA	2006/03/06	0.3 FPC CONN E/O HSG ASSY (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
	1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE		
	10 OVER	30 UNDER	±0.25	MTANAKA	2006/03/06		
	30 OVER		±0.3	APPROVED BY	DATE		
	ANGULAR	±3°		NUKITA	2006/03/06		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE	SEE TABLE		DOCUMENT NO.	SHEET NO.
			A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		SD-500797-005	2 OF 2

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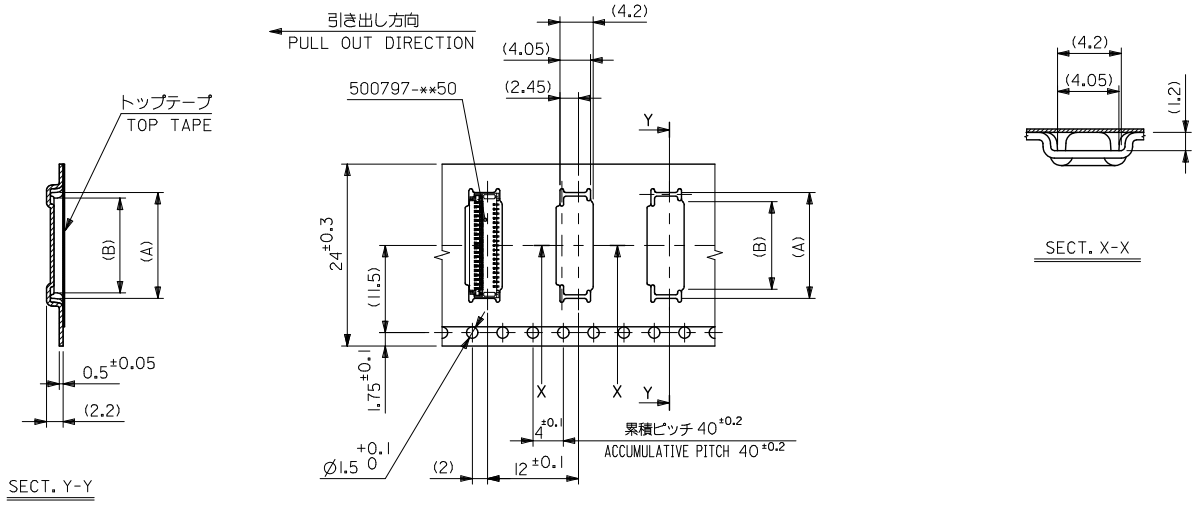
16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	17.5	3.4	5.6	500797-1194	11
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極致 Ck+
				500797-**94	MODEL No.

REVISED IEC NO. J2016-1099 G1 DRW:MTAKASHI 04/2016/04/19 CHK:DKTAKASHI 2016/04/26 APPR:IKUSUHARA01 2016/04/28 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY		---	METRIC	
	0.25 UNDER UNDER ±0.03	DRAWN BY		DATE	TITLE		
	0.25 OVER 0.5 UNDER ±0.03	YMAEDA		2006/03/07	EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-		
	0.5 OVER 4.0 UNDER ±0.1	CHECKED BY		DATE			
4.0 OVER 10 UNDER ±0.2	MTANAKA		2006/03/07				
10 OVER 30 UNDER ±0.25	APPROVED BY		DATE	DOCUMENT NO.		SHEET NO.	
30 OVER UNDER ±0.3	NUKITA		2006/03/07	SD-500797-006		2 OF 3	
ANGULAR ±3 °	MATERIAL NO.		SEE CHART				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	A3						

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	10.0	12.2	500797-3394	33
		9.4	11.6	500797-3194	31
		8.2	10.4	500797-2794	27
		7.0	9.2	500797-2394	23
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	製品番号 MATERIAL No.	極致 CK+
				500797-***94	MODEL No.

REVISED EC NO. J2016-1099 DRAWN: TAKAHASHI 04/2016/04/19 CHKD: TAKAHASHI 2016/04/26 APPR: IKUSUHARA01 2016/04/28 REV DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	±0.25	UNDER	UNDER	±0.03	MM ONLY	METRIC
	±0.25	OVER	0.5	UNDER	±0.05	
	±0.5	OVER	4.0	UNDER	±0.1	
	±1.0	OVER	10	UNDER	±0.2	
	±3.0	OVER	30	UNDER	±0.25	
	ANGULAR	±3 °	±0.3			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	SEE CHART		
			DRAWN BY YMAEDA	DATE 2006/03/07	TITLE EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.05MM) GOLD PLATING -LEAD FREE-	
			CHECKED BY MTANAKA	DATE 2006/03/07	DOCUMENT NO. SD-500797-006	
			APPROVED BY NUKITA	DATE 2006/03/07	SHEET NO. 3 OF 3	
			MATERIAL NO.			

9 8 7 6 5 4 3 2 1